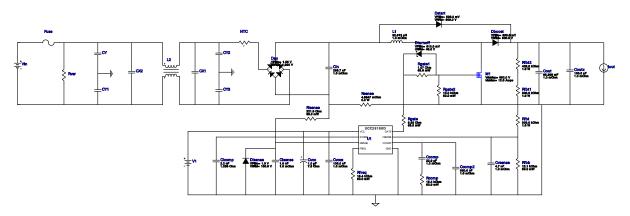


# WEBENCH® Design Report

VinMin = 210.0V VinMax = 255.0V Vout = 400.0V Iout = 7.0A Device = UCC28180DR Topology = PFC-BOOST Created = 2020-05-23 14:12:34.574 BOM Cost = NA BOM Count = 32 Total Pd =

Design: 16 UCC28180DR UCC28180DR 210V-255V to 400.00V @ 7A



1. Mosfet gate resistances are a starting point and need to be modified according to Mosfet selected. Protection circuit is designed for standard input conditions and should be redesigned for unconventional input conditions.

#### **Design Alerts**

#### UCC28180 Design

With the current design condition, suitable FET could not be found in the current database. Hence, this design is created using an ideal FET. Please note that the resulting FET parameters are ideal, so the efficiency/loss values have been disabled. Also, the schematic/PCB export and Thermal simulations will not work with the ideal FET.

### **Electrical BOM**

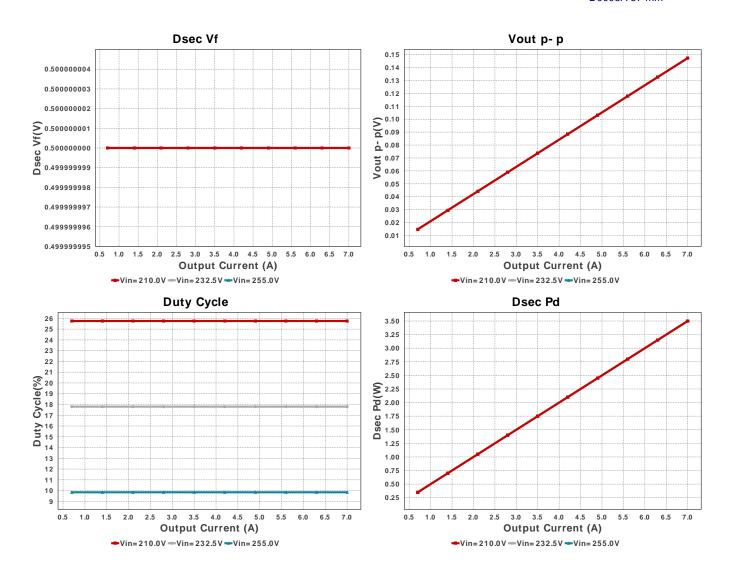
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Ccomp	Taiyo Yuden	LMK212BJ226MG-T Series= X5R	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.10	0805 7 mm <sup>2</sup>
Ccomp2	MuRata	GRM155R61A564KE15D Series= X5R	Cap= 560.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 6.0 A	1	\$0.03	0402 3 mm <sup>2</sup>
Cicomp	TDK	CGA1A2X7R1E222K030BA Series= X7R	Cap= 2.2 nF ESR= 1.26834 Ohm VDC= 25.0 V IRMS= 201.468 mA	1	\$0.01	0201_033 2 mm <sup>2</sup>
Cin	CUSTOM	CUSTOM Series= ?	Cap= 289.7 nF ESR= 1.0 mOhm VDC= 540.94 V IRMS= 19.849 A	1	NA	CUSTOM 0 mm <sup>2</sup>
Cisense	MuRata	GRM033R71C102KA01D Series= X7R	Cap= 1.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0201 2 mm <sup>2</sup>
Cout	CUSTOM	CUSTOM Series= ?	Cap= 63.396 mF ESR= 1.0 mOhm VDC= 600.0 V IRMS= 15.8776 A	1	NA	CUSTOM 0 mm <sup>2</sup>
Coutx	CUSTOM	CUSTOM Series= ?	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 600.0 V IRMS= 15.8776 A	1	NA	CUSTOM 0 mm <sup>2</sup>

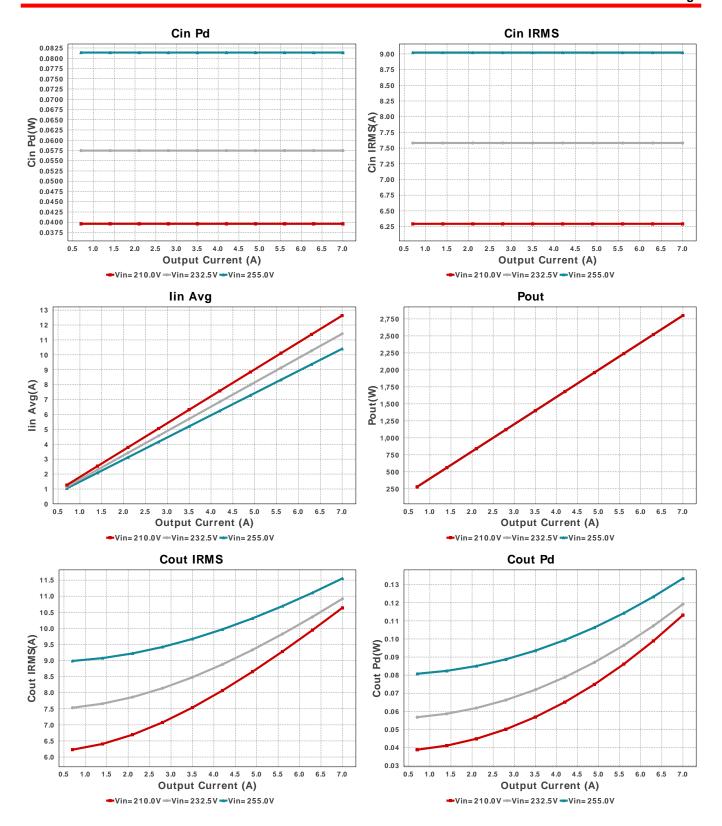
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cvcc	Vishay-Sprague	293D105X9025A2TE3 Series= 293D	Cap= 1.0 uF ESR= 7.6 Ohm VDC= 25.0 V IRMS= 100.0 mA	1	\$0.09	3216-18 11 mm <sup>2</sup>
Cvccx	MuRata	GRM155R71C104KA88D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm <sup>2</sup>
Cvsense	MuRata	GRM033R71A472KA01D Series= X7R	Cap= 4.7 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0201 2 mm <sup>2</sup>
Dac	Diodes Inc.	GBJ2510-F	VF@Io= 1.05 V VRRM= 1,000.0 V	1	\$1.09	GBJ 211 mm²
Dboost	CUSTOM	CUSTOM	VF@Io= 500.0 mV VRRM= 600.0 V	1	NA	CUSTOM 0 mm <sup>2</sup>
Disense	ON Semiconductor	1N4148	VF@Io= 1.0 V VRRM= 100.0 V	1	NA	_ <b>■</b> DO-35 40 mm²
Dstart	CUSTOM	CUSTOM	VF@Io= 500.0 mV VRRM= 600.0 V	1	NA	CUSTOM 0 mm <sup>2</sup>
Dturnoff	Comchip Technology	CDBK0540	VF@lo= 510.0 mV VRRM= 40.0 V	1	\$0.08	SOD-123F 12 mm <sup>2</sup>
L1	CUSTOM	CUSTOM	L= 92.813 μH 1.0 mOhm	1	NA	CUSTOM 0 mm <sup>2</sup>
M1	NA	IdealFET	VdsMax= 650.0 V IdsMax= 12.0 Amps	1	NA	NA 0 mm²
M1	NA	IdealFET	VdsMax= 650.0 V IdsMax= 12.0 Amps	1	NA	NA 0 mm²
NTC	GE Sensing	CL-101 Series= CL	Thermistor	1	\$2.30	CL-101 194 mm²
Rcomp	Yageo	RC0201FR-0715K4L Series= ?	Res= 15.4 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm <sup>2</sup>
Rfbb	Yageo	RC0201FR-0712K1L Series= ?	Res= 12.1 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm <sup>2</sup>
Rfbt	Vishay-Dale	CRCW2512300KJNEG Series= CRCWe3	Res= 300.0 kOhm Power= 1.0 W Tolerance= 5.0%	1	\$0.04	2512 43 mm <sup>2</sup>
Rfbt1	Vishay-Dale	CRCW2512300KJNEG Series= CRCWe3	Res= 300.0 kOhm Power= 1.0 W Tolerance= 5.0%	1	\$0.04	2512 43 mm <sup>2</sup>
Rfbt2	Vishay-Dale	CRCW2512402KFKEG Series= CRCWe3	Res= 402.0 kOhm Power= 1.0 W Tolerance= 1.0%	1	\$0.05	2512 43 mm <sup>2</sup>
Rfreq	Yageo	RC0201FR-0715K4L Series= ?	Res= 15.4 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm <sup>2</sup>
Rgate	Vishay-Dale	CRCW04023R92FKED Series= CRCWe3	Res= 3.92 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rgate1	Vishay-Dale	CRCW04021R07FKED Series= CRCWe3	Res= 1.07 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rgate2	Yageo	RC0201FR-0710KL Series= ?	Res= 10.0 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm <sup>2</sup>
Risense	Vishay-Dale	CRCW0402221RFKED Series= CRCWe3	Res= 221.0 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>

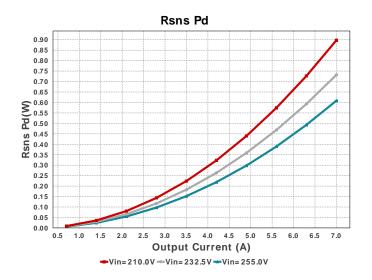
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rsense	CUSTOM	CUSTOM Series= ?	Res= 4.5547 mOhm Power= 0.0 W Tolerance= 0.0%	1	NA	CUSTOM 0 mm <sup>2</sup>
Rvar	TDK	S10K275E2		0	\$0.15	
						VAR_S10K275E2 104 mm <sup>2</sup>
U1	Texas Instruments	UCC28180DR	Switcher	1	\$0.40	

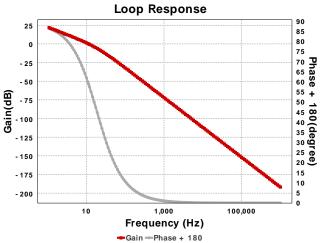


D0008A 57 mm<sup>2</sup>









## **Operating Values**

	J			
#	Name	Value	Category	Description
1.	Cin IRMS	6.47 A	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	41.858 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	10.739 A	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	115.32 mW	Capacitor	Output capacitor power dissipation
5.	Dsec Pd	3.5 W	Diode	Secondary Diode Power Dissipation
6.	Dsec Vf	500.0 mV	Diode	Effective Forward Voltage Drop at the Operating Current
7.	ICThetaJA	116.1 degC/W	IC	IC junction-to-ambient thermal resistance
8.	lin Avg	12.634 A	IC	Average input current
9.	Cin Pd	41.858 mW	Power	Input capacitor power dissipation
10.	Cout Pd	115.32 mW	Power	Output capacitor power dissipation
11.	Dsec Pd	3.5 W	Power	Secondary Diode Power Dissipation
12.	Rsns Pd	897.2 mW	Power	Current Limit Sense Resistor Power Dissipation
13.	Rsns Pd	897.2 mW	Resistor	Current Limit Sense Resistor Power Dissipation
14.	BOM Count	32	System	Total Design BOM count
			Information	
15.	Cross Freq	11.99 Hz	System	Bode plot crossover frequency
	5 . 6 .		Information	
16.	Duty Cycle	25.754 %	System	Duty cycle
4-	E	2	Information	T. 15 . B A (BOM
17.	FootPrint	1.806 k mm²	System	Total Foot Print Area of BOM components
40	F	405 707 1.11-	Information	Continue for a constant
18.	Frequency	135.707 kHz	System	Switching frequency
19.	Gain Marg	-202.678 dB	Information System	Bode Plot Gain Margin
13.	Gairriviary	-202.070 db	Information	Bode Flot Gain Margin
20.	lout	7.0 A	System	lout operating point
	1041	7.070	Information	rout operating point
21.	Low Freq Gain	22.247 dB	System	Gain at 1Hz
			Information	
22.	Mode	CCM	System	Conduction Mode
			Information	
23.	Phase Marg	57.609 deg	System	Bode Plot Phase Margin
	Ŭ	· ·	Information	<b>o</b>
24.	Pout	2.8 kW	System	Total output power
			Information	
25.	Total BOM	NA	System	Total BOM Cost
			Information	
26.	Vin	210.0 V	System	Vin operating point
			Information	, •
27.	Vout	400.0 V	System	Operational Output Voltage
			Information	
28.	Vout Actual	128.967 V	System	Vout Actual calculated based on selected voltage divider resistors
			Information	·
29.	Vout Tolerance	5.826 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider
			Information	resistors if applicable
30.	Vout p-p	146.426 mV	System	Peak-to-peak output ripple voltage
			Information	

### **Design Inputs**

Name	Value	Description	
lout	7.0	Maximum Output Current	

5

Name	Value	Description
VinMax	255.0	Maximum input voltage
VinMin	210.0	Minimum input voltage
Vout	400.0	Output Voltage
acFrequency	60.0	AC Frequency
base_pn	UCC28180	Base Product Number
source	AC	Input Source Type
Та	50.0	Ambient temperature

# WEBENCH® Assembly

#### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

#### Soldering Component to Board

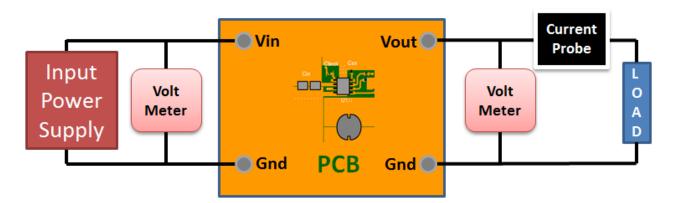
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 210.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

#### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



### **Design Assistance**

- 1. Feature Highlights: Output Current up to 23A, 85 to 265 V Input Voltage Range, Integrated Thermal Protection, Ideal for High power applications.
- 2. Master key: 78760316E94F2B0C[v1]
- 3. UCC28180 Product Folder: http://www.ti.com/product/UCC28180: contains the data sheet and other resources.

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